

Product Advisory (PA)

Subject: Package Outline Correction for 8L / SOIC-EP

Publication Date: 8/9/2019

Effective Date: 8/9/2019

Revision Description:

Initial Release

Description of Change:

This notice is to you that Renesas Electronics America Inc has updated 8 leads EPSOIC (Exposed Pad Small Outline Integrated Circuit). The updates include changes to the following:

8L / SOIC - Exposed Pad (150mil)

Package Outline Description	Symbol	From		To		From		To	
		Min (inch)	Max (inch)	Min (inch)	Max (inch)	Min (mm)	Max (mm)	Min (mm)	Max (mm)
Package Total Height	A	0.056"	0.066"	0.056"	0.067"	1.430	1.680	1.422	1.700
Package Standoff height	A1	0.001"	0.005"	0.0"	0.005"	0.030	0.130	0.000	0.130
Foot Length	L	0.016"	0.035"	0.016"	0.035"	0.410	0.890	0.406	0.890

❖ **RED** font indicated the dimension change in inches and millimeters.

Affected Product List

ISL6613AEIBZ	ISL78307FBEBZ-T	ISL78307FBECZTKR5632	ISL80410IBEZ-T7A	ISL6506ACBZ-T
ISL6613AEIBZ-T	ISL78307FBEBZ-T7A	ISL80136IBEAJZ	HIP2100EIBZ	ISL6506BCBZ
ISL78307FBEAZ	ISL78307FBEBZ-TR5506	ISL80136IBEAJZ-T	HIP2100EIBZT	ISL6506BCBZ-T
ISL78307FBEAZ-T	ISL78307FBECZ	ISL80136IBEAJZ-T7A	HIP2101EIBZ	ISL6506BCBZ-TR5418
ISL78307FBEAZ-T7A	ISL78307FBECZ-T	ISL80136IBEAJZTR5632	HIP2101EIBZ-TS2705	ISL6506BCBZA
ISL78307FBEAZ-TR5506	ISL78307FBECZ-T7A	ISL80410IBEZ	HIP2101EIBZT	ISL6506BCBZA-T
ISL78307FBEBZ	ISL78307FBECZ-TR5303	ISL80410IBEZ-T	ISL6506ACBZ	ISL6506BCBZA-TS2568

Reason for Change:

The correction to the package outline aligns the documentation with the product characteristics.

Impact on fit, form, function, quality & reliability:

This is minor package dimension update. The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via Renesas's internal traceability system.

Qualification status: Not Applicable

Sample availability: 8/9/2019

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@RENESAS.COM	Europe: PCN-EU@RENESAS.COM	Japan: PCN-JP@RENESAS.COM	Asia Pac: PCN-APAC@RENESAS.COM

Appendix A – Package Outline Drawing (POD) 8 Leads / SOIC – Exposed Pad

